



## Product Change Notification / LIAL-29JCGD899

---

**Date:**

26-Jan-2021

**Product Category:**

8-bit Microcontrollers

**PCN Type:**

Manufacturing Change

**Notification Subject:**

CCB 4439 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products available in 8L DFN (4x4x0.9mm) package at MMT assembly site

**Affected CPNs:**

[LIAL-29JCGD899\\_Affected\\_CPN\\_01262021.pdf](#)

[LIAL-29JCGD899\\_Affected\\_CPN\\_01262021.csv](#)

**Notification Text:****PCN Status:**

Final notification

**PCN Type:**

Manufacturing Change

**Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products available in 8L DFN (4x4x0.9mm) package at MMT assembly site

**Pre Change:**

Using gold (Au) bond wire

**Post Change:**

Using gold (Au) or palladium coated copper with gold flash (CuPdAu) bond wire

**Pre and Post Change Summary:**

|                           | Pre Change                          | Post Change                         |        |
|---------------------------|-------------------------------------|-------------------------------------|--------|
| Assembly Site             | Microchip Technology Thailand (MMT) | Microchip Technology Thailand (MMT) |        |
| Wire material             | Au                                  | Au                                  | CuPdAu |
| Die attach material       | 3280                                | 3280                                |        |
| Molding compound material | G700LTD                             | G700LTD                             |        |
| Lead frame material       | A194                                | A194                                |        |

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire at MMT assembly site.

**Change Implementation Status:**

In Progress

**Estimated First Ship Date:**

February 01, 2021 (date code: 2106)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

|                               | November 2020 |    |    |    | → | January 2021 |    |    |    |    | February 2021 |    |    |    |
|-------------------------------|---------------|----|----|----|---|--------------|----|----|----|----|---------------|----|----|----|
| Workweek                      | 45            | 46 | 47 | 48 |   | 01           | 02 | 03 | 04 | 05 | 06            | 07 | 08 | 09 |
| Initial PCN Issue Date        | X             |    |    |    |   |              |    |    |    |    |               |    |    |    |
| Qual Report Availability      |               |    |    |    |   |              |    |    |    | X  |               |    |    |    |
| Final PCN Issue Date          |               |    |    |    |   |              |    |    |    | X  |               |    |    |    |
| Estimated Implementation Date |               |    |    |    |   |              |    |    |    |    | X             |    |    |    |

**Method to Identify Change:**

Traceability code

**Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report

**Revision History:**

**November 5, 2020:** Issued initial notification.

**January 26, 2021:** Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on February 01, 2021.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachments:**

[PCN\\_LIAL-29JCGD899\\_Qual\\_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

**Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.